
Copy of New Claims 13 - 21:

13. A resin composition used for fabricating an interlayer dielectric of a printed wiring board, wherein said composition, comprises; a) an epoxy based resin comprising epoxy resins having two or more glycidyl groups per molecule; b) a phenol novolak epoxy resin curing agent containing triazine rings within a molecule; c) maleimide compounds having thermosetting properties; d) polymers having crosslinkable functional groups within a molecule; and e) a crosslinker, which is added if necessary; wherein said resin composition is free of halogen.

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14. The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 13, wherein said epoxy based resin is selected from the group consisting of bisphenol A epoxy resin, bisphenol F epoxy resin, novolak epoxy resin, cresol novolak epoxy resin, glycidylamine epoxy resin, and combinations thereof.

15. The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 13, wherein said polymers having crosslinkable functional groups are selected from the group consisting of polyether sulfone resin having a terminal hydroxyl group, polyvinyl acetal resin having repeated hydroxyl groups, phenoxy resin, and combinations thereof.

16. The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 13, wherein said epoxy resin curing agent is selected from the group

consisting of melamine, benzoguanamine, a compound obtained from a condensation reaction of phenols and formaldehydes; and combinations thereof.

17. The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 13, wherein said maleimide groups are selected from the group consisting of N,N'-(4,4-diphenylmethane)bismaleimide; bis(3-ethyl-5-methyl-4-maleimidephenyl)methane; 2,2-bis[4-(4-maleimidephenoxy)phenyl]propane; thermosetting maleimide compounds obtained from Michael addition reaction of these maleimide compounds and polyamines; and combinations thereof.

18. A method for producing a resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 13, wherein said resin composition is added to and dissolved in the solvent to a solids content of 40 to 50 % by weight, wherein 100 parts of said resin composition comprises: 20 to 70 parts by weight of an epoxy based resin; 10 to 50 parts by weight of maleimide compounds having thermosetting properties; 5 to 30 parts by weight of polymers having crosslinkable functional groups within a molecule; and a balance being a crosslinker added as necessary and an epoxy resin curing agent containing 5 to 25% by weight nitrogen.

19. A method for producing the resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 18, wherein the solvent is a mixed

solvent of N-methylpyrrolidone and methyl ethyl ketone, the mixing weight ratio of N-methylpyrrolidone/methyl ethyl ketone being in a range of 50/50 to 40/60.

20. A printed wiring board comprising a plurality of layers including an interlayer dielectric, the interlayer dielectric comprising a resin composition, wherein said composition comprises; a) an epoxy based resin; b) an epoxy resin curing agent containing 5 to 25% by weight nitrogen; c) maleimide compounds having thermosetting properties; d) polymers having crosslinkable functional groups within a molecule; and e) a crosslinker, which is added if necessary, wherein said resin composition is free of halogen.

21. A printed wiring board comprising a plurality of layers including an interlayer dielectric, the interlayer dielectric comprising a resin composition, wherein said composition comprises; a) an epoxy based resin comprising epoxy resins having two or more glycidyl groups per molecule; b) a phenol novolak epoxy resin curing agent containing triazine rings within a molecule; c) maleimide compounds having thermosetting properties; d) polymers having crosslinkable functional groups within a molecule; and e) a crosslinker, which is added if necessary; wherein said resin composition is free of halogen.